300mm Fully-Automatic Multifunction Wafer Mounter





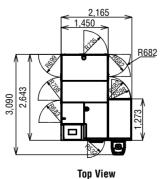
Outline

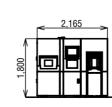
- -Fully-automatic wafer mounter suited for ultra-thin wafer manufacturing, with the following functions:
- · UV irradiation to BG Tape · Alignment
- · Wafer mounting · BG Tape peeling
- -Ability to operate in-line with DISCO Corporation's DFG8000 series back grinder or DGP8000 series grinder/polisher.
- -Corresponds to DBG process.
- -Prevents wafer damage by reducing wafer handling frequency down to 4 times "stand-alone," and 2 times "in-line."

Options ·Host Communication Function (Communication Format :

- Conforms to SECS-I and HSMS/Software : Conforms to GEM)
- ·Vision System (Wafer ID Reader & Barcode Attachment System)
- ·Dicing Tape In-line Pre-cutting
- ·DBG Process Compatibility
- ·In-line Operation with DISCO Corporation DFG8000 series or DGP8000 series
- Suitable Tapes ·Dicing tape : Adwill D series, G series ·Dicing die bonding tape : Adwill LE Tape

External View





Front View

Contact:Advanced Materials Operations

Right Side View

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Unit:mm

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Facility		
Power Supply	Voltage Frequency Phase Power consumption	: AC200 (±10%) : 50/60Hz : 3 phase : 8.0kW (200VAC)
Air Supply	Air pressure Air consumption	: 0.6-0.8MPa : >800L/min (ANR)
Vacuum Supply	Vacuum pressure	: >-80kPa
Applicable Wafer Size	200mm, 300mm	
Size	Width : 2,165mm	
	Depth : 3,090mm	A A A A A A
	Height : 1,800mm	
	(excluding the signal to	ower and protruding parts)
Weight	3,100kg	
UPH	45wafers/hour	
The above processing cap	acity is based on follo	owing conditions ("stand-

will give you the Advantage

alone"):

- Wafer : 300mm diameter non-polished mirror wafer
- Ring frame : for 300mm wafer
- Dicing tape : G-18 from LINTEC
- Back grinding tape : E-8180HR from LINTEC